

85V N-Channel Trench MOSFET(Preliminary)

General Description

- Trench Power technology
- Low R_{DS(ON)}
- Low Gate Charge
- Optimized for fast-switching applications

Applications

- Synchronous Rectification in DC/DC and AC/DC Converters
- Isolated DC/DC Converters in Telecom and Industrial

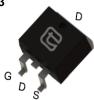
Product Summary

 V_{DS} 85V I_{D} (at $V_{GS} = 10V$) 115A $R_{DS(ON)}$ (at $V_{GS} = 10V$) < 7.8m Ω

100% UIS Tested

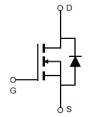


TO-263









Part Number	Part Number Package Type		Marking
TTB115N08AA	TO-263	Tape&Reel	TTB115N08AA
TTP115N08AA	TO-220	Tube	TTP115N08AA

Absolute Maximum Ratings (T_A =25°C unless otherwise noted)

Parameter		Symbol	Maximum	Units
Drain-Source Voltage		V _{DS}	85	V
Gate-Source Voltage		V_{GS}	±20	V
Continuous Prain Current B	T _C =25°C	I _D	105	
Continuous Drain Current B	T _C =100°C		80	Α
Pulsed Drain Current ^A		I _{DM}	345	А
Avalanche Current A		I _{AS}	57	А
Single Pulse Avalanche Energy L =0.3mH ^A		E _{AS}	487	mJ
Davier Discipation C	T _C =25°C	_	200	W
Power Dissipation ^C	T _C =100°C	- P _D	100	W
Junction and Storage Temperature Range		T_J , T_{STG}	-55 to 175	°C
Thermal Characteristics				

Thermal Characteristics

Parameter		Symbol	Maximum	Units
Maximum Junction-to-Case	Steady-State	$R_{\Theta JC}$	0.75	00.044
Maximum Junction-to-Ambient	Steady-State	$R_{\Theta JA}$	100	°C/W



		Conditions		Value			
Symbol	Parameter			Min	Тур	Max	Units
STATIC P	ARAMETERS	•				•	•
BV _{DSS}	Drain-Source Breakdown Voltage	I _D =250μA,V _{GS} =0V		85			V
			T _J =25°C			1	
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 85V, V_{GS} = 0V$	T _J =100°C			25	μA
I _{GSS}	Gate-Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 20V$,			±100	nA
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$		2	3	4	V
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =10V, I _D =30A			6.4	7.8	mΩ
g _{FS}	Forward Transconductance	V _{DS} =5V, I _D =20A			80		S
V_{SD}	Diode Forward Voltage	I _S =20A, V _{GS} =0V				1.2	V
Is	Maximum Body-Diode Continuous Curre	nt ^B				105	Α
DYNAMIC	PARAMETERS						
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =40V, f =1MH _Z			6650		pF
C _{oss}	Output Capacitance				302		
C _{rss}	Reverse Transfer Capacitance				261		
R_g	Gate Resistance	f =1MH _Z			2.5		Ω
SWITCHI	NG PARAMETERS						
Q_g	Total Gate Charge	V _{GS} =10V,V _{DS} =40V, I _D =20A			112		
Q_{gs}	Gate Source Charge				35		nC
Q_{gd}	Gate Drain Charge				23		
t _{D(on)}	Turn-On Delay Time	Time $V_{GS} = 10V, V_{DS} = 40V, I_{D} = 20A,$ $R_{G} = 2.5\Omega$			24		
t _r	Turn-On Rise Time				19		ns
$T_{D(off)}$	Turn-Off Delay Time				70		
t _f	Turn-Off Fall Time				30		
t _{rr}	Body Diode Reverse Recovery Time				37		ns
Q _{rr}	Body Diode Reverse Recovery Charge			_	58		nC

- A. Single pulse width limited by maximum junction temperature.
- B. The maximum current rating is package limited.
- C. The power dissipation P_D is based on $T_{J(MAX)}$ =175°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.

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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

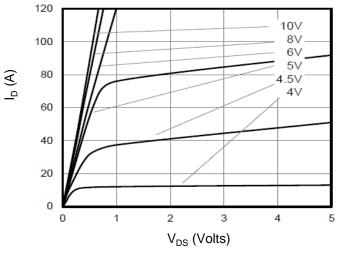


Figure 1: On-Region Characteristics

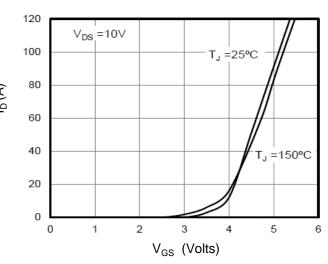


Figure 2: Transfer Characteristics

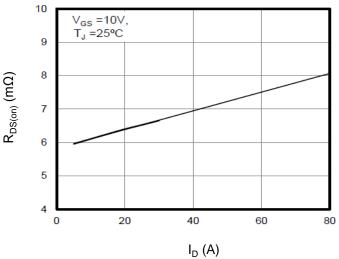


Figure 3: On-Resistance vs. Drain Current

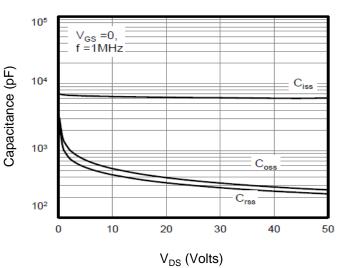


Figure 4: Capacitance Characteristics

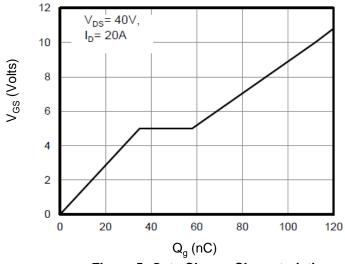


Figure 5: Gate Charge Characteristics

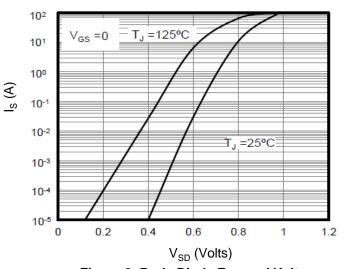


Figure 6: Body Diode Forward Voltage

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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

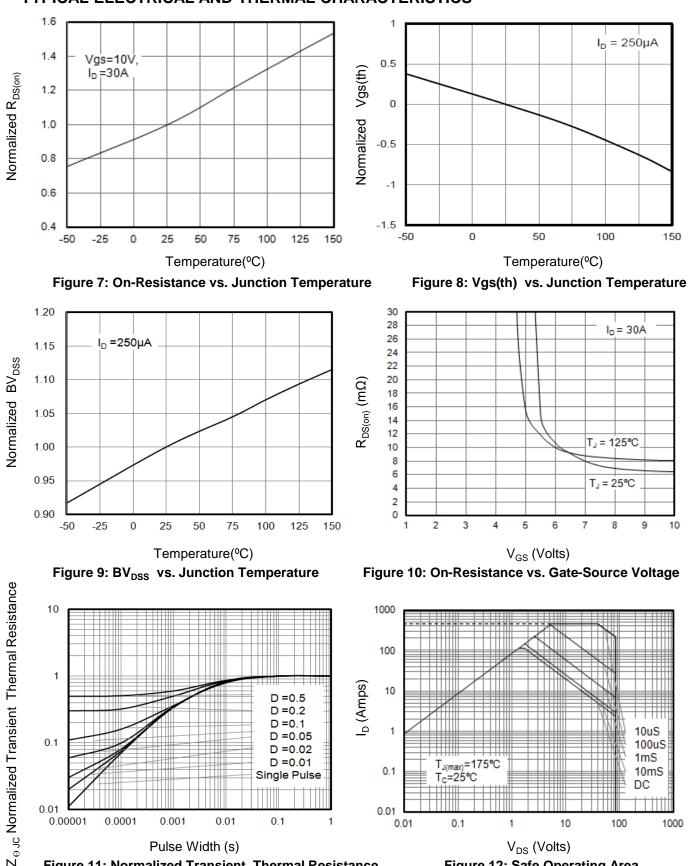


Figure 11: Normalized Transient Thermal Resistance

Pulse Width (s)

0.01

0.1

0.001

0.0001

0.00001

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0.01

0.1

100

V_{DS} (Volts)

Figure 12: Safe Operating Area

1000



Figure A: Gate Charge Test Circuit and Waveforms

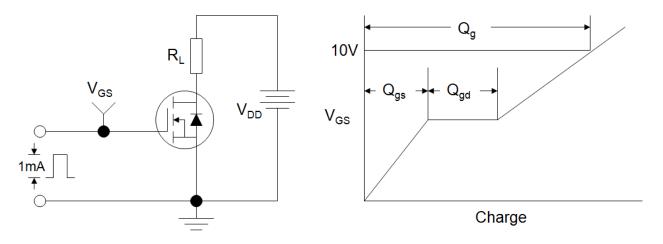


Figure B: Resistive Switching Test Circuit and Waveforms

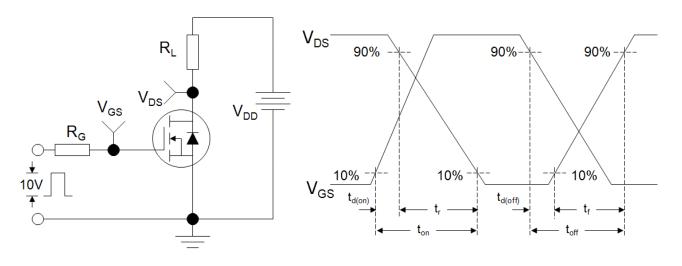
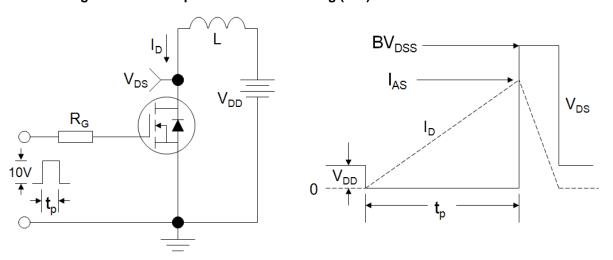


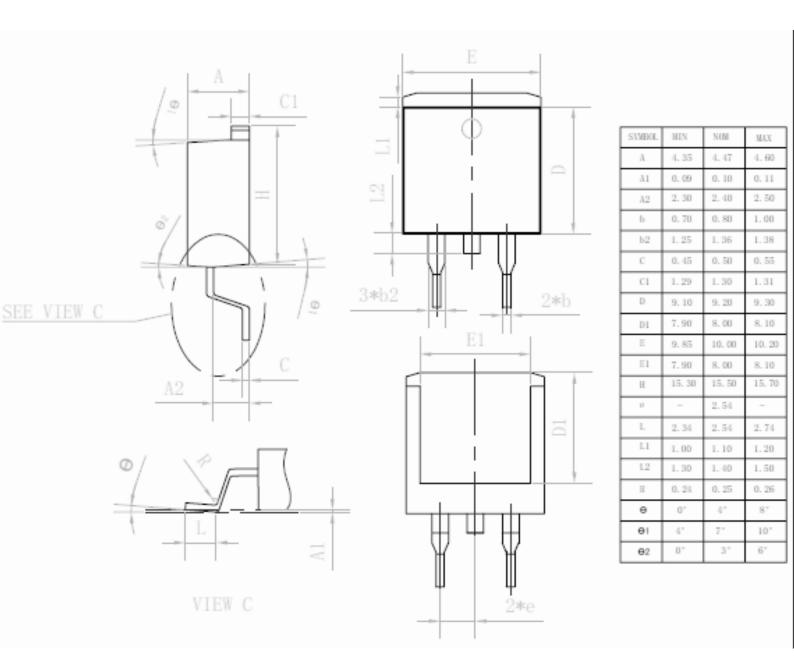
Figure C: Unclamped Inductive Switching (UIS) Test Circuit and Waveforms



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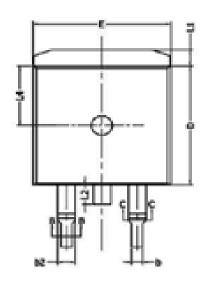


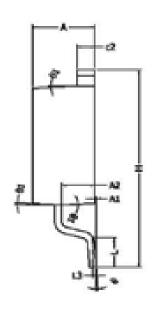
TO-263(E)

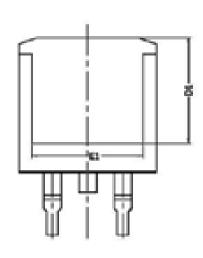




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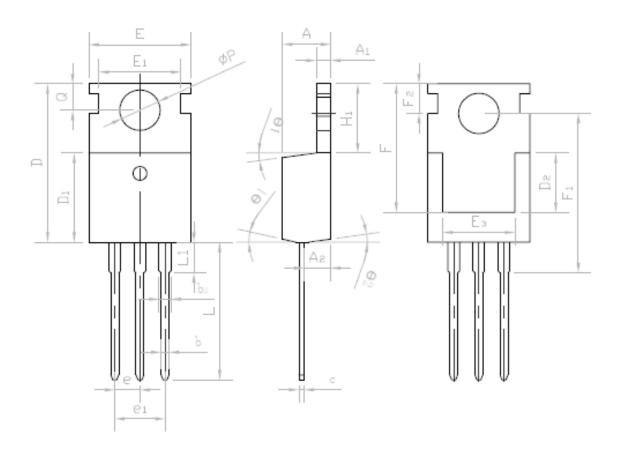


COMMON DIMENSIONS (UNITS OF MEASURE -MILLIMETER)

SYMBOL	MIN	NOM	MAX
A	4.40	4.50	4.60
A1	0	0.10	0.25
A2	2.20	2.40	2.60
ь	0.76		0.89
b1	0.75	0.80	0.85
b2	1.23		1.37
63	1.22	1.27	1.32
С	0.47		0.60
c1	0.46	0.51	0.56
c2	1.25	1.30	1.35
D	9.10	9.20	9.30
D1	8.00		-
E	9.80	9.90	10.00
E1	7.80		-
e	2.	54 BSC	
H	14.90	15.30	15.70
L	2.00	2.30	2.60
Li	1.17	1.27	1.40
L2			1.75
L3	0.258SC		
L4	4.60 REF		
8	0.	-	8*
01	1*	3*	5°



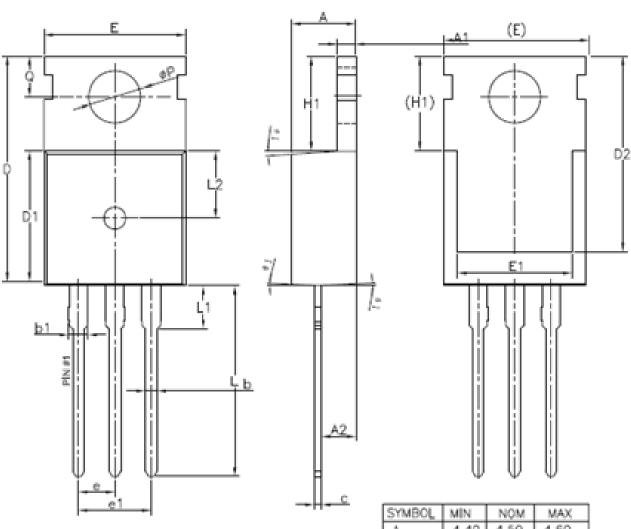
TO-220(E)

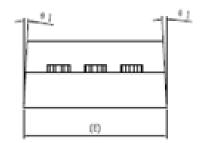


SYMBOL	MIN	NOM	MAX	
A	4.27	4.57	4.07	
As	1.15	1.30	1.45	
A _c	2.10	2.40	2.70	
ь	0.70	0.80	1.00	
b _c	1.17	1.27	1.50	
G	0.40	0.50	0.65	
D	15.10	15.60	16.10	
Du	8.80	9.10	9.40	
D:	5.70	6.70	7.00	
E	9.70	10,00	10.30	
E1	-	8.70	-	
E.	9.63	10.00	10.35	
Ea	7.00	9.00	8.40	
	2.5	54 BS	С	
e.	5/	08 BS	С	
Hı	6.00	6.50	6.85	
L	12.75	13.50	13.90	
L1	-	3.10	3.40	
#P	3.45	3.60	3.75	
0	2.60	2.80	3.00	
Θ.	4*	7*	10*	
0,	0*	3.	6.	
F	13.30	13.50	13.70	
F	15.50	15.90	16.30	
Fe	2.80	3.00	3.20	



TO-220(I)





SYMBOL	MIN	NOM	MAX
A	4.40	4.50	4.60
A1	1.27	1.30	1.33
A2	2.30	2.40	2.50
b	0.70	_	0.90
b1	1.27	_	1.40
С	0.45	0.50	0.60
D	15.30	15.70	16.10
D1	9.10	9.20	9.30
02	13.10	-	13.70
Ε	9.70	9.90	10.20
E1	7.80	8.00	8.20
e	2.54BSC		
e1		5.08BSC	
H1	6.30	6.50	6.70
L	12.78	13.08	13.38
L1	_	_	3.50
L2	4.60REF		
øP	3.55 3.60		3.65
0	2.73	_	2.87
0.1	1"	3.	5



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